TEXAS INSTRUMENTS

TPD2S017

SLLS949B – SEPTEMBER 2009 – REVISED DECEMBER 2015

TPD2S017 2-Channel Ultra-Low Clamp Voltage ESD Solution With Series-Resistor Isolation

1 Features

- Ultra-Low Clamping Voltage Ensures the Protection of Ultra-Low Voltage Core Chipset During ESD Events
- IEC 61000-4-2 ESD Protection
- Matching of Series Resistor (R = 1 Ω) of ±8 mΩ (Typical)
- Differential Channel Input Capacitance Matching of 0.02 pF (Typical)
- High-Speed Data Rate and EMI Filter Action at High Frequencies (–3 dB Bandwidth, ≠3 GHz)
- Available in 6-Pin Small-Outline Transistor [SOT-23 (DBV)] Package
- Easy Straight-Through Routing Packages

2 Applications

- Hi-Speed USBs
- IEEE 1394 Interfaces
- Low-Voltage Differential Signaling (LVDS)
- Mobile Display Digital Interfaces (MDDI) and Mobile Industry Processor Interfaces (MIPI)
- HS Signals

3 Description

The TPD2S017 is a two channel electrostatic discharge (ESD) protection device. This protection product offers two-stage ESD transient voltage suppression (TVS) diodes in each line with a typically 1-Ω series resistor isolation. This architecture allows the device to clamp at a very low voltage during system level ESD strikes.

The TPD2S017 conforms to the IEC61000-4-2 ESD protection standard. Due to the series resistor component, the TPD2S017 provides a controlled filter roll-off for even greater spurious EMI suppression and signal integrity. The monolithic silicon technology allows good matching of the component values, including the clamp capacitances and the series resistors between the differential signal pairs. The tight matching of the line capacitance and series resistors ensures that the differential signal distortion due to added ESD clamp remains minimal, and it also allows the part to operate at high-speed differential data rate (in excess of 1.5 Gbps). The DBV package offers a flow-through pin mapping for ease of board layout.

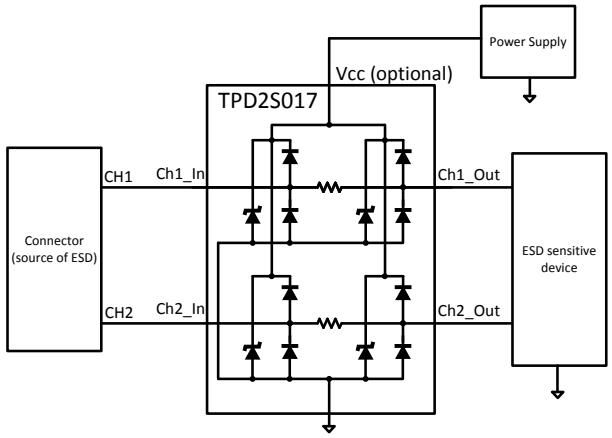
Typical applications of this ESD protection device are circuit protection for USB data lines, IEEE 1394 Interfaces, LVDS, MDDI/MIPI and HS signals.

Device Information(1)

PART NUMBER	PACKAGE	BODY SIZE (NOM)
TPD2S017	SOT-23 (6)	2.90 mm × 1.60 mm

(1) For all available packages, see the orderable addendum at the end of the data sheet.

Application Schematic



An IMPORTANT NOTICE at the end of this data sheet addresses availability, warranty, changes, use in safety-critical applications, intellectual property matters and other important disclaimers. PRODUCTION DATA.

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4 Revision History

NOTE: Page numbers for previous revisions may differ from page numbers in the current version.

Changes from Revision A (July 2015) to Revision B **Page**

- Added *ƒ = 10 MHz* to the test condition of *IO capacitance* in the *Electrical Characteristics* table ... 4

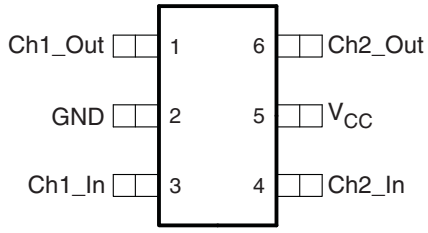
Changes from Original (September 2009) to Revision A **Page**

- Added *Pin Configuration and Functions* section, *ESD Ratings* table, *Feature Description* section, *Device Functional Modes*, *Application and Implementation* section, *Power Supply Recommendations* section, *Layout* section, *Device and Documentation Support* section, and *Mechanical, Packaging, and Orderable Information* section ... 1

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5 Pin Configuration and Functions

DBV Package
6-Pin SOT-23
Top View



Pin Functions

PIN		I/O	DESCRIPTION
NAME	NO.		
Ch1_In	3	I	High-speed ESD clamp input
Ch2_In	4		
Ch1_Out	1	O	High-speed ESD clamp output
Ch2_Out	6		
GND	2	—	Ground
V_{CC}	5	—	Optional power

6 Specifications

6.1 Absolute Maximum Ratings

over operating free-air temperature range (unless otherwise noted)(1)

		MIN	MAX	UNIT
V_{IO}	IO voltage	0	5	V
T_A	Operating temperature	–40	85	°C
T_{stg}	Storage temperature	–85	125	°C

(1) Stresses beyond those listed under *Absolute Maximum Ratings* may cause permanent damage to the device. These are stress ratings only, which do not imply functional operation of the device at these or any other conditions beyond those indicated under *Recommended Operating Conditions*. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

6.2 ESD Ratings

			VALUE	UNIT
$V_{(ESD)}$	Electrostatic discharge	Human body model (HBM), per ANSI/ESDA/JEDEC JS-001(1)	±15000	V
		Charged-device model (CDM), per JEDEC specification JESD22-C101(2)	±1500	
		IEC 61000-4-2 Contact Discharge	±11000	

(1) JEDEC document JEP155 states that 500-V HBM allows safe manufacturing with a standard ESD control process.
(2) JEDEC document JEP157 states that 250-V CDM allows safe manufacturing with a standard ESD control process.

6.3 Recommended Operating Conditions

over operating free-air temperature range (unless otherwise noted)

		MIN	NOM	MAX	UNIT
Operating free-air temperature, T_A		–40		85	°C
Operating voltage	V_{CC}	0		5	V
	Ch1_In	0		V_{CC}	
	Ch2_In	0		V_{CC}	

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6.4 Thermal Information

THERMAL METRIC[1]		TPD2S017 DBV (SOT-23) 6 PINS	UNIT
$R_{\theta JA}$	Junction-to-ambient thermal resistance	192.7	°C/W
$R_{\theta JC(top)}$	Junction-to-case (top) thermal resistance	166.2	°C/W
$R_{\theta JB}$	Junction-to-board thermal resistance	39.8	°C/W
ψ_{JT}	Junction-to-top characterization parameter	44.7	°C/W
ψ_{JB}	Junction-to-board characterization parameter	39.4	°C/W
$R_{\theta JC(bot)}$	Junction-to-case (bottom) thermal resistance	N/A	°C/W

(1) For more information about traditional and new thermal metrics, see the *Semiconductor and IC Package Thermal Metrics* application report, SPRA953.

6.5 Electrical Characteristics

over operating free-air temperature range (unless otherwise noted)

PARAMETER		TEST CONDITIONS	MIN	TYP	MAX	UNIT
R	Series resistor			1		Ω
I_{IO}	Current from I/O pins	V_{IO} = 3 V		0.01	0.1	µA
ΔRS	Channel-to-channel resistance match	V_{IO} = 3 V		±8	±15	mΩ
V_D	Diode forward voltage for lower clamp	I_D = 8 mA	–0.6	–0.8	–0.95	V
R_{DYN}	Dynamic resistance (for I/O clamp)	I = 9 A		0.8		Ω
C_{IO}	IO capacitance	V_{IO} = 2.5 V; f = 10 MHz		1		pF
V_{BR}	Break-down voltage	I_O = 1 mA	11	12		V

6.6 Dissipation Ratings

PACKAGE	$T_A \leq 25°C$ POWER RATING	DERATING FACTOR[1] ABOVE $T_A \leq 25°C$	$T_A = 70°C$ POWER RATING
DBV	463.18 mW	–4.63 mW/C	254.75 mW

(1) Derating factor is defined as the inverse of the traditional junction-to-ambient thermal resistance ($R_{\theta JA}$).

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6.7 Typical Characteristics

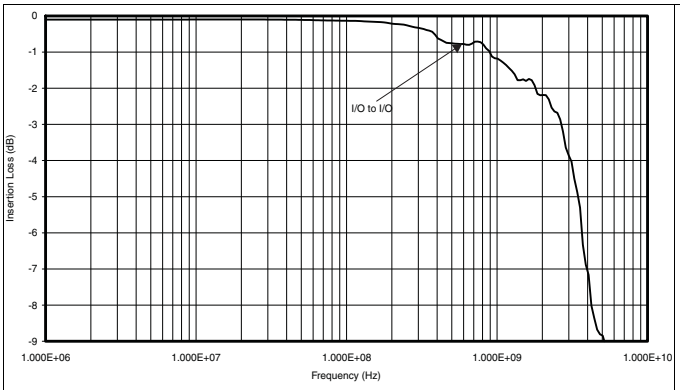


Figure 1. Insertion Loss Data (S21)

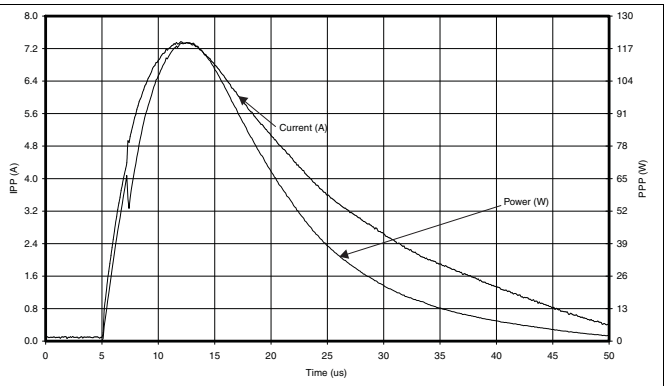


Figure 2. Peak Pulse Waveforms
Ch1_Out, PUT with respect to GND, V_{CC} = 5 V

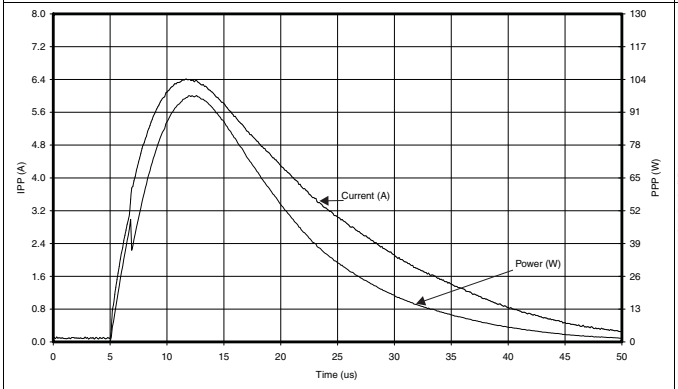


Figure 3. Peak Pulse Waveforms
Ch2_In, PUT with respect to GND, V_{CC} = 5 V

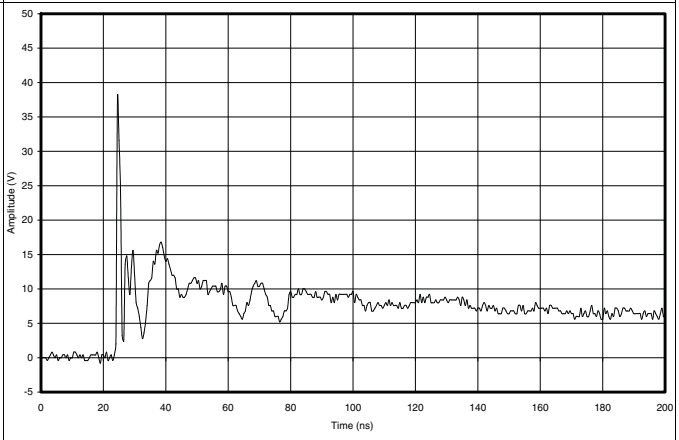


Figure 4. IEC Clamping Waveforms
8-kV Contact, 1-GHz Bandwidth

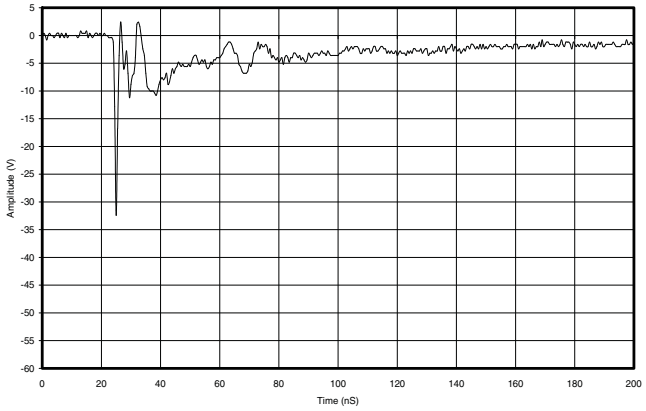


Figure 5. IEC Clamping Waveforms
–8-kV Contact, 1-GHz Bandwidth

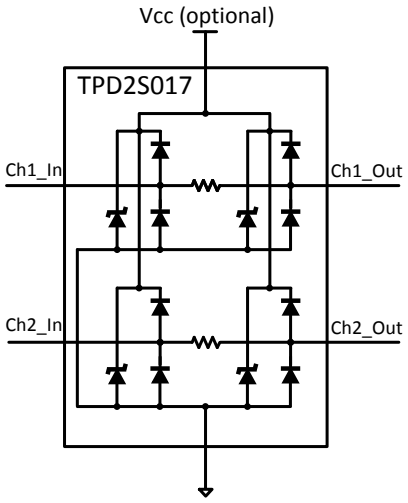
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7 Detailed Description

7.1 Overview

The TPD2S017 is a two-channel ESD protection device. The two-stage ESD diodes and 1-Ω isolation resistor topology of the device gives the system very robust and good protection during ESD strikes. The TPD2S017 conforms to the IEC61000-4-2 ESD protection standard. The TPD2S017 provides a –3-dB frequency at almost 3 GHz which provides enough bandwidth for a vast majority of applications. Thanks to the monolithic silicon technology, the tight matching of the line capacitances and series resistances ensures a minimum distorted differential signal and a high operating differential data rate. The DBV package offers a flow-through pin mapping for ease of board layout.

7.2 Functional Block Diagram



7.3 Feature Description

Each channel of the TPD2S017 device has a topology of two-stage clamps with isolation resistor. This topology optimizes the clamping performance while supporting a high bandwidth. Due to the low clamping voltage, the down stream circuits that connect to the output of the channels are well-protected. The high IEC 61000-4-2 level ensures the system's robustness during the ESD events. The good matching of the resistor and capacitance values will yield minimal distortion of the signals. The low resistance and capacitance values make sure that this device supports a high differential data rate. The flow-through pinout ensures no additional layout burden on the printed circuit board (PCB).

7.4 Device Functional Modes

The TPD2S017 device stays passive and has low leakage during normal operation when the voltage at the input of each channel is from 0 V to V_{CC} and activates when that voltage exceeds one forward diode drop above V_{CC} or below ground. During IEC ESD events, contact transient voltages as high as ±11 kV can be suppressed. When the voltages on the protected lines fall below the trigger voltage, the device reverts back to the low leakage passive state.

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8 Application and Implementation

NOTE

Information in the following applications sections is not part of the TI component specification, and TI does not warrant its accuracy or completeness. TI's customers are responsible for determining suitability of components for their purposes. Customers should validate and test their design implementation to confirm system functionality.

8.1 Application Information

When a system contains a human interface connector, it becomes vulnerable to large system-level ESD strikes that standard ICs cannot survive. Protection products are typically used to suppress ESD at these connectors. TPD2S017 is a two-channel ESD protection device. In each channel, it contains two-stage TVS diodes and a resistor between the two clamping stages as an isolation. This implementation provides good clamping performance, minimal signal distortion and the support of high data speed.

8.2 Typical Application

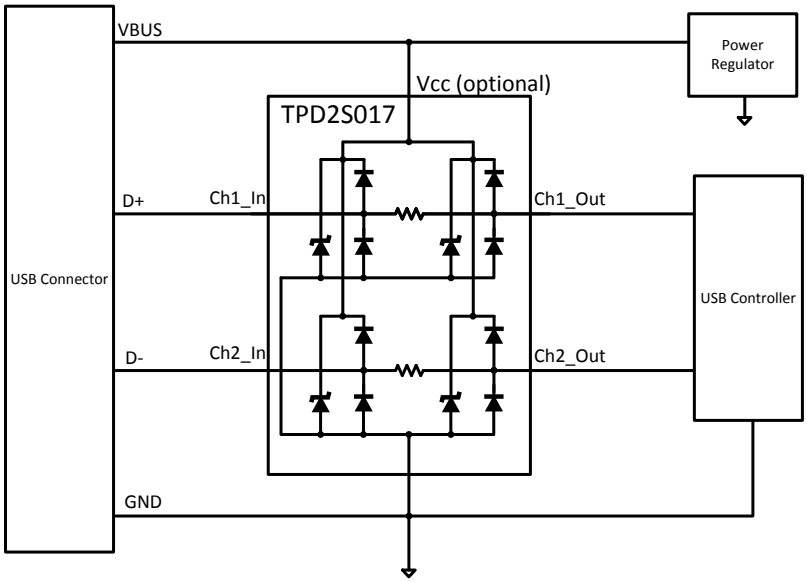


Figure 6. Typical Application Schematic

8.2.1 Design Requirements

For this design example, a TPD2S017 will be used to protect the USB 2.0 high-speed data lines. The following system parameters are known.

Table 1. Design Parameters

DESIGN PARAMETER	VALUE
High-speed mode high-level output voltage	400 mV ±10%
High-speed mode low-level output voltage	0 V ± 10 mV
USB 2.0 high-speed data rate	480 Mbps
Required IEC 61000-4-2 ESD Protection	±8-kV Contact

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8.2.2 Detailed Design Procedure

To begin the design process, some parameters must be decided upon; the designer should make sure:

- Voltage range on the protected lines must not go beyond one forward diode drop above the V_{CC} and must no go below one forward diode drop below the ground.
- Operating frequency is supported by the IO capacitance C_{IO}.
- IEC 61000-4-2 protection requirement is covered by the IEC performance of the TVS diode.

For this application, a high speed USB 2.0 signal that ranges from –10 mV to 440 mV will be applied to each line. Connect a 5-V power supply to V_{CC} pin; therefore, the signal will not fall outside of the normal operation range and the TPD2S017 will stay passive and low leakage during normal operation.

Next, consider the data rate of this signal and ensure that the TVS I/O capacitance will not distort this signal by filtering it. The speed of a USB 2.0 high-speed signal is 480 Mbit/s. With TPD2S017's ultra low IO capacitance, this device can support 1.5 Gbit/s data rate and thus can pass USB 2.0 high-speed signal with minimal distortion.

Finally, TPD2S017 is rated for the IEC 61000-4-2 (Level 4) so it provides sufficient system-level ESD protection to the human interface in this application. See *Layout Example* for instructions on properly laying out TPD2S017.

8.2.3 Application Curves

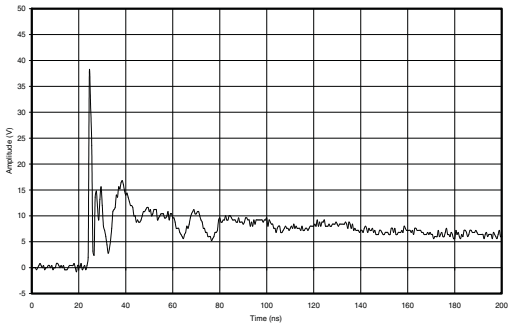


Figure 7. IEC Clamping Waveforms 8-kV Contact, 1-GHz Bandwidth

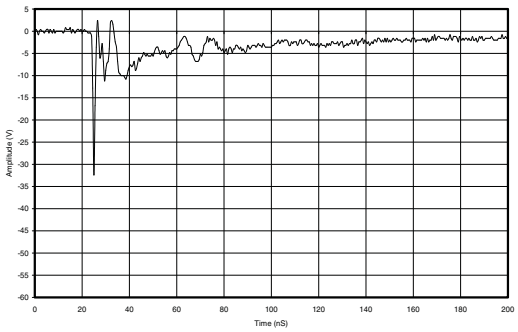


Figure 8. IEC Clamping Waveforms –8-kV Contact, 1-GHz Bandwidth

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9 Power Supply Recommendations

The optional V_{CC} power supply bias is recommended to lower the I/O capacitances. Ensure that the maximum voltage specifications for each pin are not violated.

10 Layout

10.1 Layout Guidelines

- The optimum placement is as close to the connector as possible.
  - EMI during an ESD event can couple from the trace being struck to other nearby unprotected traces, resulting in early system failures.
  - The PCB designer must minimize the possibility of EMI coupling by keeping any unprotected traces away from the protected traces which are between the TVS and the connector.
- Route the protected traces as straight as possible.
- Eliminate any sharp corners on the protected traces between the TVS and the connector by using rounded corners with the largest radii possible.
  - Electric fields tend to build up on corners, increasing EMI coupling.
- Use thick and short traces for the power and ground paths.
- Run differential signal lines in pair with small distance to optimize signal integrity.

10.2 Layout Example

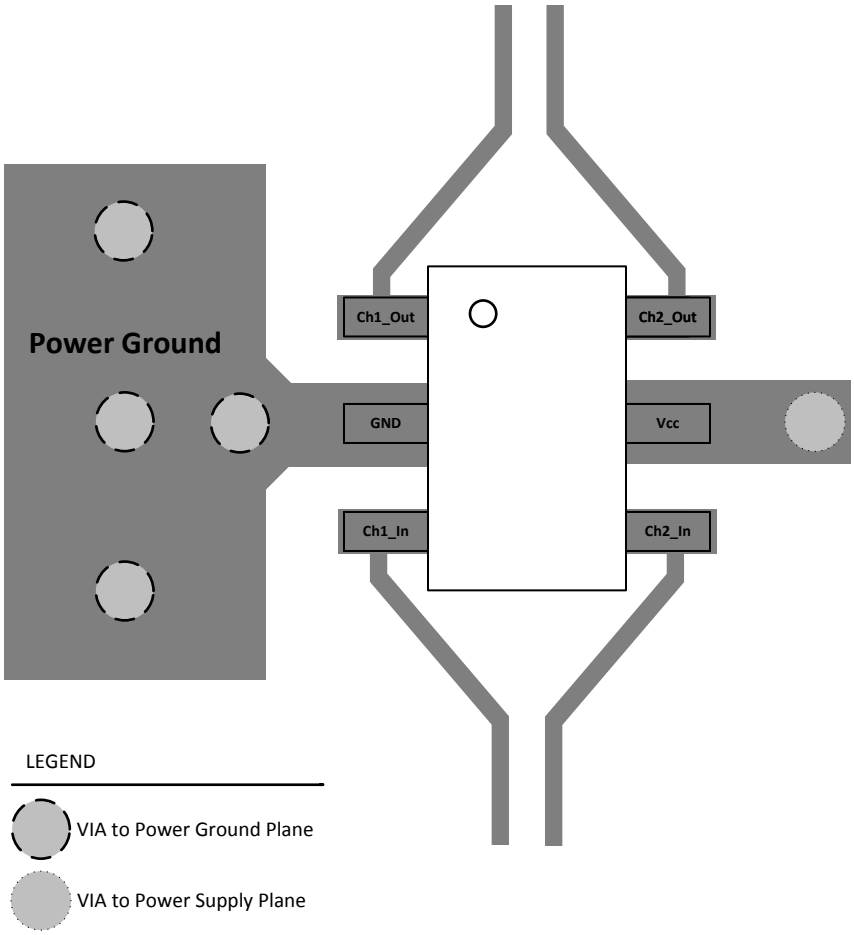


Figure 9. Layout Recommendation

11 Device and Documentation Support

11.1 Community Resources

The following links connect to TI community resources. Linked contents are provided "AS IS" by the respective contributors. They do not constitute TI specifications and do not necessarily reflect TI's views; see TI's Terms of Use.

TI E2E™ Online Community ***TI's Engineer-to-Engineer (E2E) Community.*** Created to foster collaboration among engineers. At e2e.ti.com, you can ask questions, share knowledge, explore ideas and help solve problems with fellow engineers.

Design Support ***TI's Design Support*** Quickly find helpful E2E forums along with design support tools and contact information for technical support.

11.2 Trademarks

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11.3 Electrostatic Discharge Caution



These devices have limited built-in ESD protection. The leads should be shorted together or the device placed in conductive foam during storage or handling to prevent electrostatic damage to the MOS gates.

11.4 Glossary

SLYZ022 — *TI Glossary*.

This glossary lists and explains terms, acronyms, and definitions.

12 Mechanical, Packaging, and Orderable Information

The following pages include mechanical, packaging, and orderable information. This information is the most current data available for the designated devices. This data is subject to change without notice and revision of this document. For browser-based versions of this data sheet, refer to the left-hand navigation.

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PACKAGING INFORMATION

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead/Ball Finish (6)	MSL Peak Temp (3)	Op Temp (°C)	Device Marking (4/5)	Samples
TPD2S017DBVR	ACTIVE	SOT-23	DBV	6	3000	Green (RoHS & no Sb/Br)	CU SN	Level-1-260C-UNLIM	-40 to 85	NFT	Samples

(1) The marketing status values are defined as follows:
ACTIVE: Product device recommended for new designs.
LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.
NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.
PREVIEW: Device has been announced but is not in production. Samples may or may not be available.
OBSOLETE: TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check http://www.ti.com/productcontent for the latest availability information and additional product content details.
TBD: The Pb-Free/Green conversion plan has not been defined.
Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.
Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.
Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

(3) MSL, Peak Temp. - The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

(4) There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.

(5) Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.

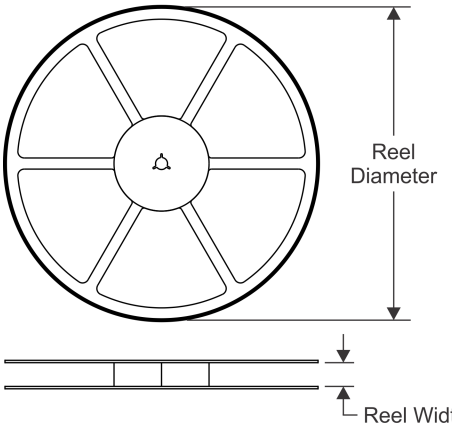
(6) Lead/Ball Finish - Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead/Ball Finish values may wrap to two lines if the finish value exceeds the maximum column width.

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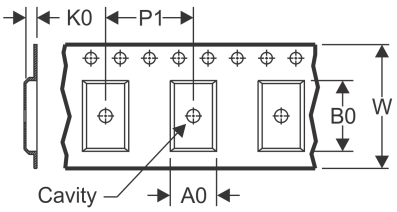
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TAPE AND REEL INFORMATION

REEL DIMENSIONS

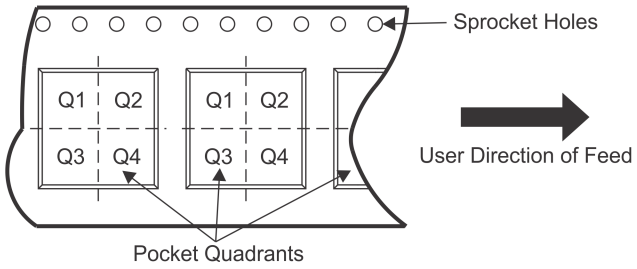


TAPE DIMENSIONS



A0	Dimension designed to accommodate the component width
B0	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

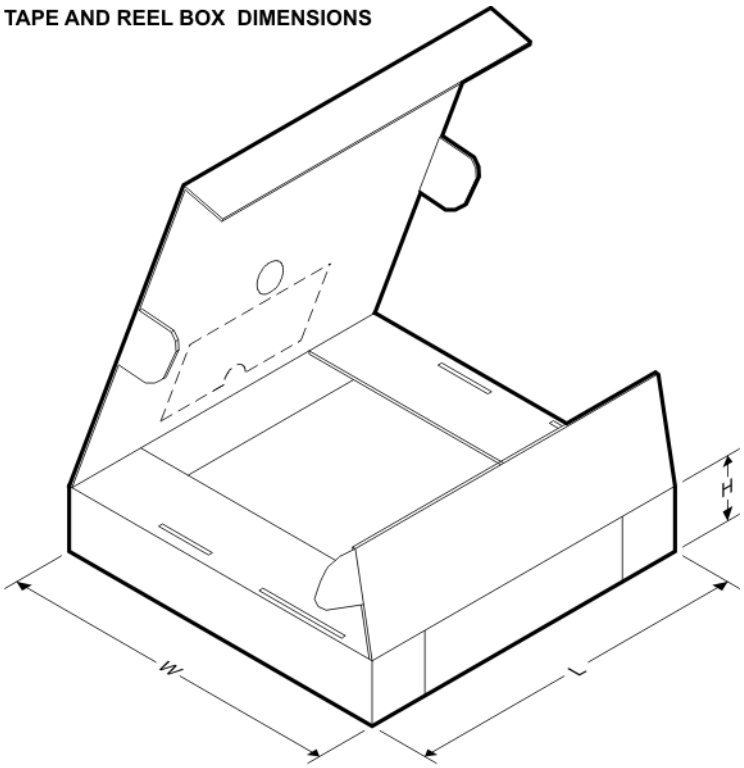
QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
TPD2S017DBVR	SOT-23	DBV	6	3000	178.0	9.0	3.23	3.17	1.37	4.0	8.0	Q3

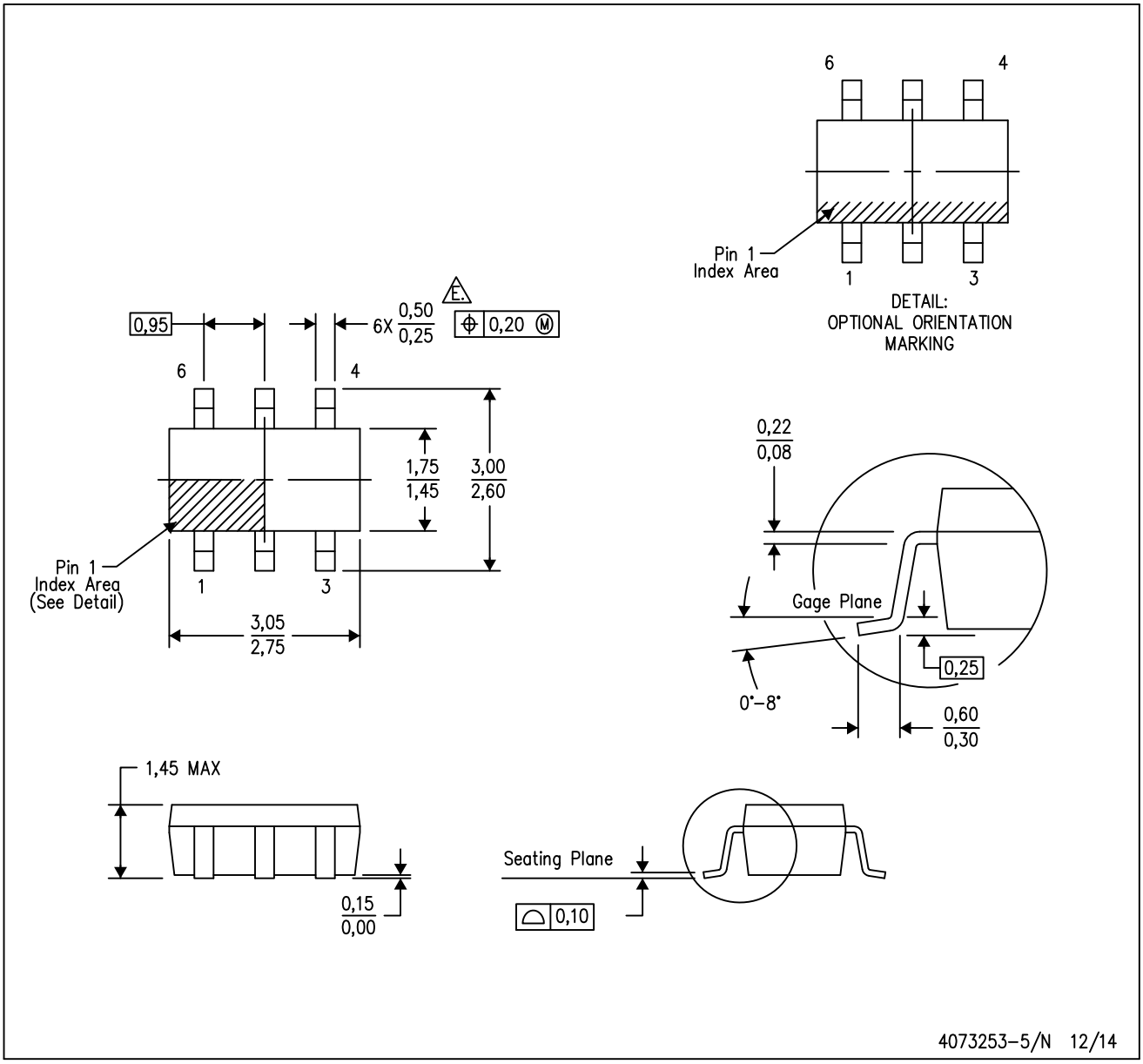
TAPE AND REEL BOX DIMENSIONS



*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
TPD2S017DBVR	SOT-23	DBV	6	3000	180.0	180.0	18.0

DBV (R–PDSO–G6) PLASTIC SMALL–OUTLINE PACKAGE



NOTES:
A. All linear dimensions are in millimeters.
B. This drawing is subject to change without notice.
C. Body dimensions do not include mold flash or protrusion. Mold flash and protrusion shall not exceed 0.15 per side.
D. Leads 1,2,3 may be wider than leads 4,5,6 for package orientation.
E. Falls within JEDEC MO–178 Variation AB, except minimum lead width.

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